



SEMI® INTERNATIONAL STANDARDS

Fiducial Mark Interoperability TF Report

As of September 11, 2015

TF Leadership (No Change)

- H. Tsunobuchi / KEYENCE
Traceability Committee
- T. Nakai / SUMCO
Silicon Wafer Committee
- S. Mashiro / Tokyo Electron
Physical Interface and Carrier Committee
- S. Masuchi / DISCO
Assembly and Package Committee
- M. Matsuda / Hitachi Kokusai
Information and Control Committee

Recent TF activity

- TF meeting on April 27, 2015 and June 11, 2015
- T7 issues
 - Traceability Japan TC Chapter assigned following up activity for T7 to Fiducial Mark Interoperability TF
 - Section 2.1 (T7 adoption of non-silicon materials)
 - Figure 3 small modification
 - M20 coordinate system (based on negative to 5752 [withdrawn])
 - TF decided to delete all position specifications from SEMI T7 because position specifications are also described on SEMI M1 and other related Silicon Standard.
 - SNARF was approved by GCS. (SNARF 5890)
 - Document 5890 is submitting to Cycle 7.
 - To be adjudicated at the next JA TC Chapter meeting of Traceability TC in conjunction with SEMICON JAPAN 2015.
- Others
 - Silicon: Give up to develop new Standard for 450mm Development Wafer with fiducial Mark
 - Assembly and Packaging: Discussing backend alignment issues with introducing fiducial mark wafer.

Next Meeting

- TBD (around the end of October)
 - T7 Revision
 - Ballot result discussion of Document 5890